

Customer Code: _____

DATASHEET

DAPU P/N: DPX3216M000012B0

| DAPU | | | Customer Approval |
|------------------|---------|----------|------------------------|
| Drew | Audited | Approved | Stamp, please! Thanks! |
| Jack | David | William | |
| Date: 2022.05.27 | | | |

Guangdong Dapu Telecom Technology Co.,Ltd

Building 5, No.24, Industrial East Road, Songshanhu Park, Dongguan, Guangdong, P.R. China

TEL: 0086-0769-88010888 FAX: 0086-0769-81800098

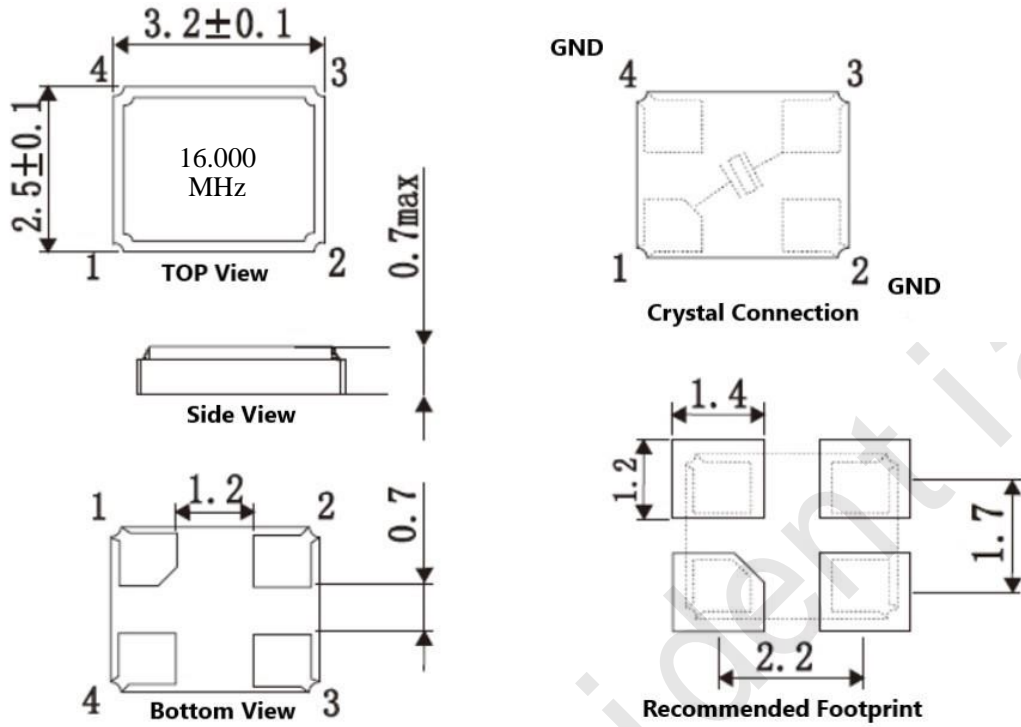


1、Electrical Parameters

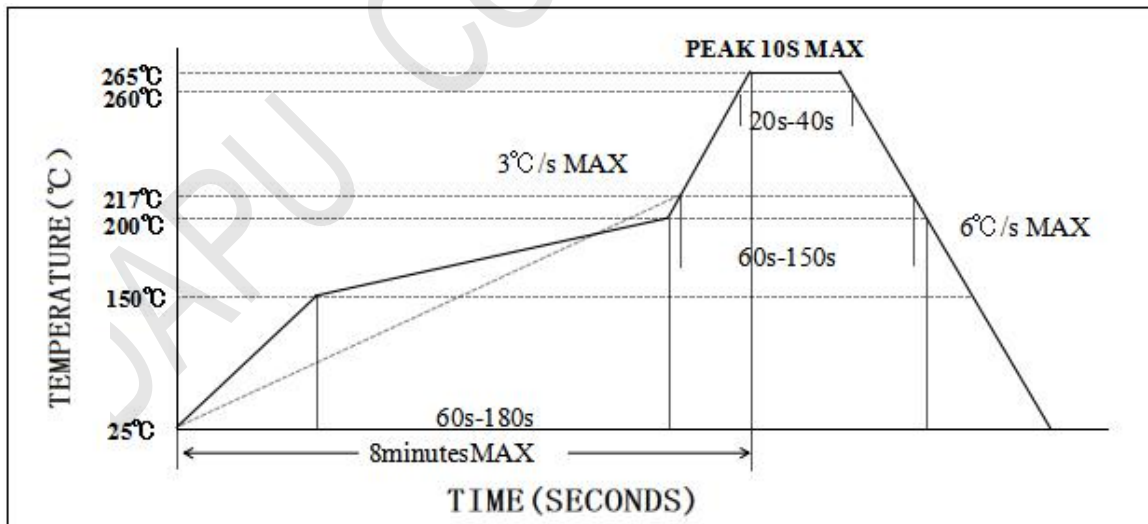
| MODEL: DPX3216M000012B0 | | | | | | | |
|-------------------------|------------------------------|------|------------------|------|------|------------------|----------------------------------|
| No. | Parameters | SYM. | Electrical Spec. | | | | Notes |
| | | | Min. | Typ. | Max. | Units | |
| 1 | Nominal Frequency | FL | 16.00 | | | MHz | |
| 2 | Oscillation Mode | - | Fundamental | | | | |
| 3 | Load Capacitance | CL | 12 | | | pF | |
| 4 | Frequency Tolerance | - | -10 | | +10 | $\times 10^{-6}$ | At 25°C |
| 5 | Frequency Stability | - | -30 | | +30 | $\times 10^{-6}$ | Over Operating Temperature Range |
| 6 | Operating Temperature | Topr | -40 | ~ | +85 | °C | |
| 7 | Storage Temperature | Tstg | -55 | | +125 | °C | |
| 8 | Drive Level | DL | 1 | 100 | 200 | μ W | |
| 9 | Equivalent Series Resistance | ESR | | | 100 | Ω | |
| 10 | Shunt Capacitance | - | | | 3.0 | pF | |
| 11 | Insulation Resistance | IR | 500 | | | M Ω | At DC 100V |
| 12 | Aging | - | -3 | | +3 | $\times 10^{-6}$ | First year at 25°C |



2、Mechanical Structure(mm)

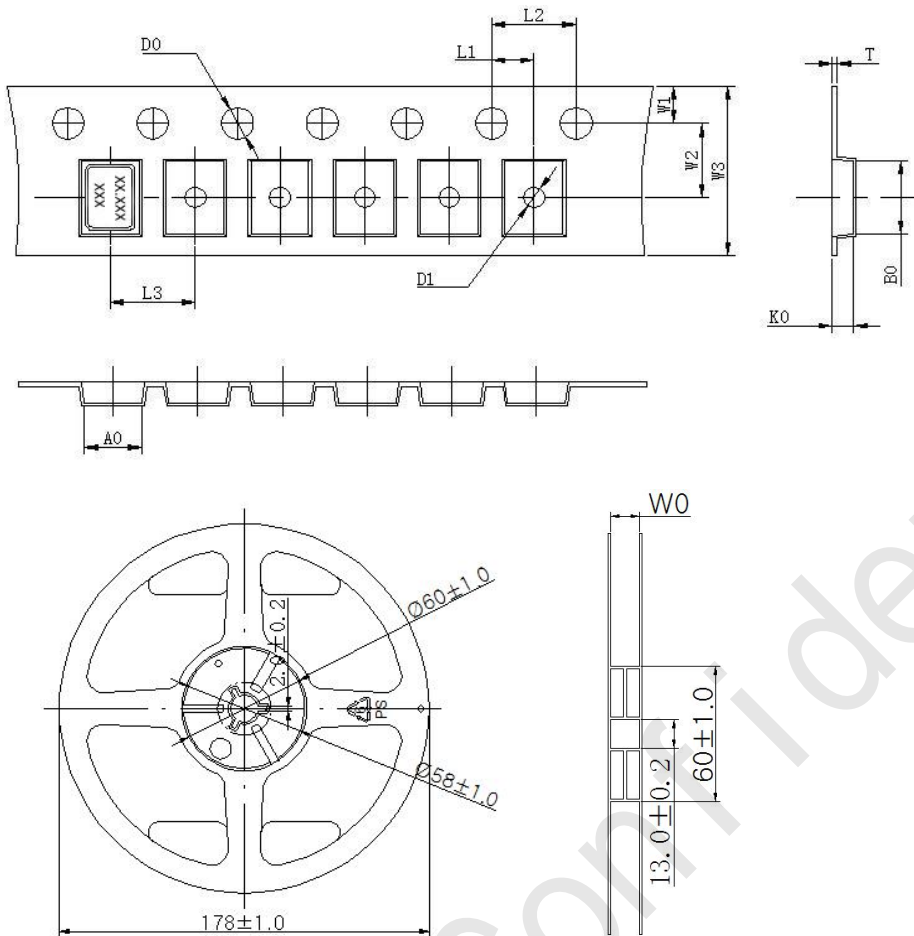


3、Reflow Soldering Curve(RoHS)





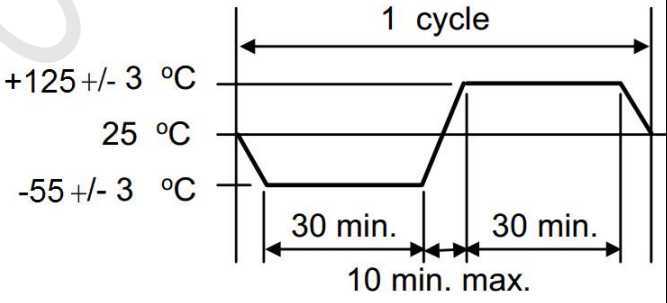
4、 Package: Tape & Reel (mm)



| | |
|----|-----------|
| L1 | 2.00±0.1 |
| L2 | 4.00±0.1 |
| L3 | 4.00±0.1 |
| D0 | 1.50±0.1 |
| D1 | 1.00±0.1 |
| W0 | 8.30±0.2 |
| W1 | 1.75±0.1 |
| W2 | 3.50±0.1 |
| W3 | 8.00±0.1 |
| A0 | 2.72±0.1 |
| B0 | 3.46±0.1 |
| K0 | 1.00±0.1 |
| T | 0.25±0.05 |



5、 Reliability Test Specification

| NO. | Test Items | Test Standard | Test Condition | Specifications |
|-----|--|---------------|---|---|
| 1 | Drop test | GB/T2423.8 | Drop from 150cm height on 3cm hard wooden board for 3 times. | Electrical performance meets specification requirements |
| 2 | Mechanical shock | GB/T2423.5 | Peak: 100g; Waveform: Half-sine; Velocity Change: 1000m/s ² ; Duration: 0.5ms; 3 times/direction, Direction: +X, -X, +Y, -Y, +Z, -Z. | |
| 3 | Vibration | GB/T2423.10 | Frequency: 10~2000Hz; Vibration:20min, 1.52mm; Direction: X, Y, Z; Duration: 2 hours/direction. | |
| 4 | Solderability | IEC60068-2-58 | Solder bath temperature:245±5°C; Dwell time:3±0.5 seconds; Solder: 100% tin. | |
| 5 | Resistance to soldering heat | IEC60068-2-58 | Solder temperature 260±5°C; Immersion time:10±1S; Solder bath composition:100% tin. | |
| 6 | High temperature storage | GB/T2423.2 | Temperature: 125°C±2°C; Duration: 500±12hours. | |
| 7 | Low temperature storage | GB/T2423.1 | Temperature: -40°C±2°C; Duration: 500±12hours. | |
| 8 | Temperature Shock | GB/T2423.22 | Do 10 cycles at the following temperature  | |
| 9 | High temperature high humidity storage | GB/T2423.3 | Temperature: 85°C±3°C; Humidity: 85%; Duration: 500hours. | |